



1. (Amended) A frame for semiconductor ~~package~~packages comprising plural lead frames arranged in a matrix through grid-leads, the grid-leads having terminals ~~projected~~which project therefrom~~from the grid leads~~ and terminals of adjacent pairs of lead frames are connected to one another at respective connection areas, ~~in which~~ ~~respective~~ semiconductor devices ~~are being~~ being respectively mounted on die-pads supported with suspending leads of individual lead frames, the semiconductor devices ~~are being~~ collectively molded with molding compound, and the collectively molded semiconductor devices ~~are being~~ cut along the grid-leads into individual semiconductor packages ~~at grid frames~~, wherein thin parts are formed ~~in areas corresponding to neighborhood of the adjacent roots of individual terminals, the terminal roots being disposed in the respective connection areas defined between interconnected pairs of terminals of adjacent lead frames.~~

2. (Amended) ~~A~~The frame for ~~semiconductor package~~ as ~~elaimed in claim~~of Claim 1, wherein the thin parts are formed by ~~half-cutting by etching~~ half-etching metal ~~of the~~at the connection areas from the front or back ~~thereof~~of the frame.

3. (Amended) A frame for semiconductor ~~package~~packages comprising plural lead frames arranged in a matrix through grid-leads, the grid-leads having terminals ~~projected~~which project therefrom~~from the grid leads~~ and terminals of adjacent pairs of lead frames are connected to one another at respective connection areas, ~~in which~~ ~~respective~~ semiconductor devices ~~are being~~ being respectively mounted on die-pads supported with suspending leads of individual lead frames, the semiconductor devices ~~are being~~ collectively molded with molding compound, and the collectively molded semiconductor

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devices ~~are~~being cut along the grid-leads into individual semiconductor packages ~~at grid frames~~, wherein hollows are formed ~~in areas corresponding to neighborhood of the adjacent~~ roots of individual terminals, the terminal roots being disposed in the respective connection areas defined between interconnected pairs of terminals of adjacent lead frames.

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ABSTRACT OF THE DISCLOSURE

A frame-F for semiconductor ~~package~~packages has die-pads ~~3~~-supported with suspending leads-2 of individual lead frames-10. Semiconductor devices are mounted on the respective die-pads-3. These semiconductor devices are collectively molded with molding ~~compounds~~compound, and then the collectively molded semiconductor packages are cut into individual packages by means of a dicing saw. In the frame-F, thin parts are formed in areas corresponding to ~~neighborhood of~~ the roots of individual terminals, the thin parts being formed by half-cutting ~~by etching~~etching metal of the areas from the front or back thereof.

~~Or~~Alternatively, hollows are formed in areas corresponding to ~~neighborhood of~~ the roots of individual terminals-7. ~~Accordingly, it is inhibited that increased sectional area of terminals is formed, so that intervals between adjacent terminals-5 are sufficiently kept. Accordingly, accidents such as soldered bridge do not occur.~~